



Vishay Siliconix

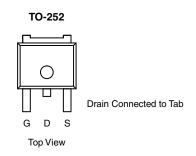
# P-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)			
- 40	0.013 at V <sub>GS</sub> = - 10 V	- 55.7 <sup>c</sup>			
	$0.022$ at $V_{GS} = -4.5 \text{ V}$	- 44.4			

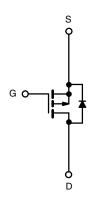
### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- Compliant to RoHS Directive 2002/95/EC





Ordering Information: SUD50P04-13L-GE3 (Lead (Pb)-free and Halogen-free)



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C, unless otherwise noted)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		$V_{DS}$	- 40	٧		
Gate-Source Voltage		$V_{GS}$	± 20			
0 .: D : 0 .h	T <sub>C</sub> = 25 °C	1	- 55.7 <sup>c</sup>			
Continuous Drain Current <sup>b</sup>	T <sub>C</sub> = 100 °C	l <sub>D</sub>	- 35.2			
Pulsed Drain Current	I <sub>DM</sub>	- 100				
Continuous Source Current (Diode Conduction)	I <sub>S</sub>	- 52 <sup>c</sup>				
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	- 40			
Avalanche Energy	L = 0.1 IIII	E <sub>AS</sub>	80	mJ		
M : D D: : : h	T <sub>C</sub> = 25 °C	В	78 <sup>b</sup>	101		
Maximum Power Dissipation <sup>b</sup>	T <sub>A</sub> = 25 °C		3 <sup>a</sup>	W		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Mariana Indiana Andriana	t ≤ 10 s	R <sub>thJA</sub>	15	18	°C/W	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State		40	50		
Maximum Junction-to-Case (Drain)		R <sub>thJC</sub>	1.3	1.8		

### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. See SOA curve for voltage derating.
- c. Calculated based on maximum allowed junction temperature. Package limitation current is 50 A.

# SUD50P04-13L-GE3

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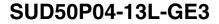


Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$ $V_{GS} = 0 \text{ V, I}_{D} = -250 \mu\text{A}$		- 40			V	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$			- 3.0	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
7 0		V <sub>DS</sub> = - 40 V, V <sub>GS</sub> = 0 V			- 1	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 40 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			- 50		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 50			Α	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A		0.0105	0.013		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A, T <sub>J</sub> = 125 °C			0.020	Ω	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 20 A		0.017	0.022		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 30 A	15			S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			3120		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		440			
Reverse Transfer Capacitance	C <sub>rss</sub>			320			
Gate Resistance	$R_g$	f = 1 MHz		4.3		Ω	
Total Gate Charge <sup>c</sup>	$Q_g$			63	95		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = -20 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -50 \text{ A}$		13		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			16			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = - 20 V, $R_L$ = 0.4 $\Omega$		18	30	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong -50 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 2.5 \Omega$		60	90		
Fall Time <sup>c</sup>	t <sub>f</sub>			47	70		
Drain-Source Body Diode Characteristic	s						
Pulse Current	I <sub>SM</sub>				- 100		
Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>F</sub> = - 50 A, V <sub>GS</sub> = 0 V		- 1.0	- 1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = - 50 A, dl/dt = 100 A/μs		36	55	ns	

### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

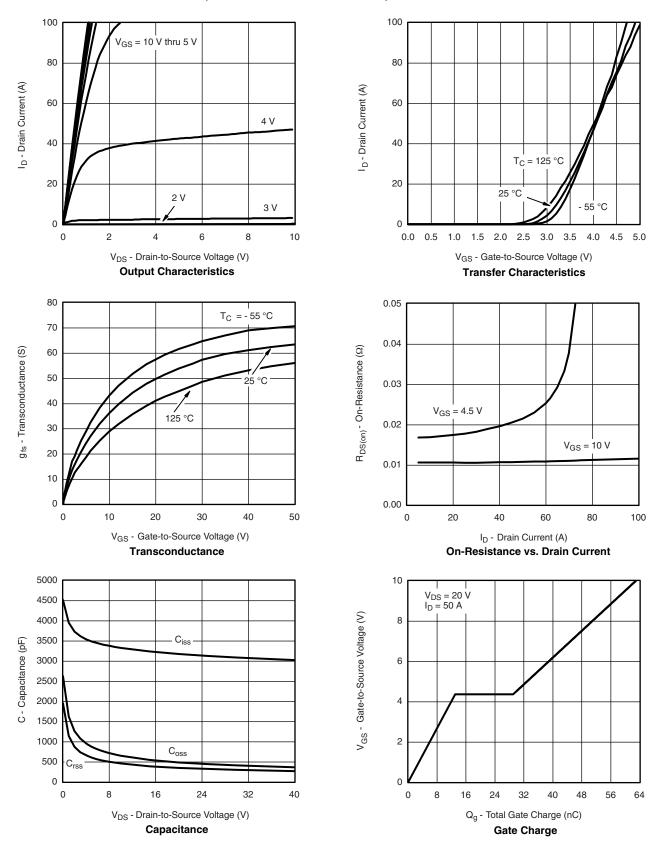
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





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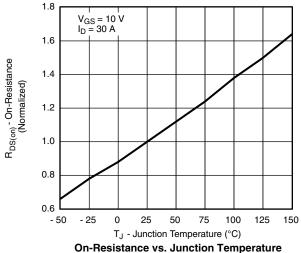
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

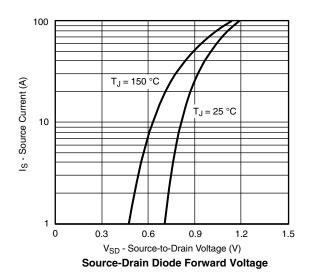


# SUD50P04-13L-GE3

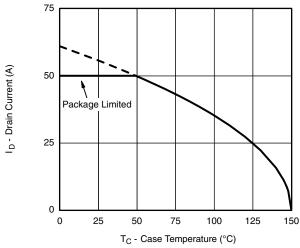
# Vishay Siliconix

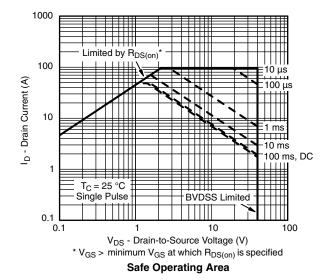
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



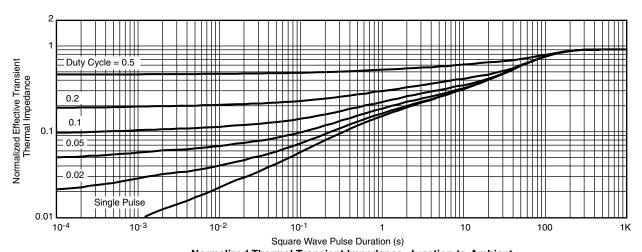


## THERMAL RATINGS





**Maximum Avalanche Drain Current** vs. Case Temperature

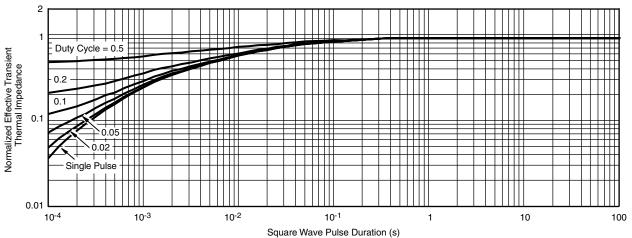




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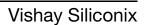
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### **THERMAL RATINGS**



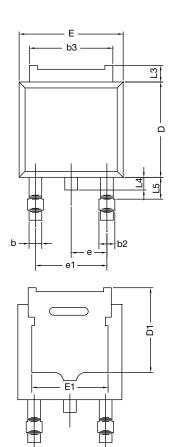
Normalized Thermal Transient Impedance, Junction-to-Case

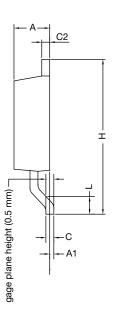
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?67069">www.vishay.com/ppg?67069</a>.





## **TO-252AA Case Outline**



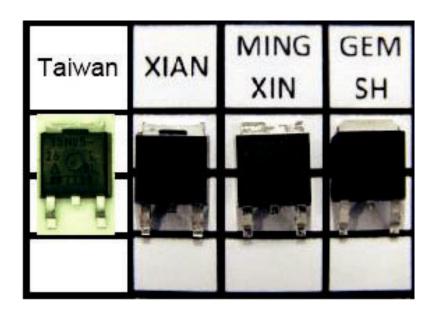


	MILLIMETERS		INC	HES		
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	4.10	-	0.161	-		
Е	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28 BSC		0.090 BSC			
e1	4.56	4.56 BSC 0.180 BSC		BSC		
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.01	1.52	0.040	0.060		
ECN: T13-0359-Rev. O, 03-Jun-13						

DWG: 5347

### Notes

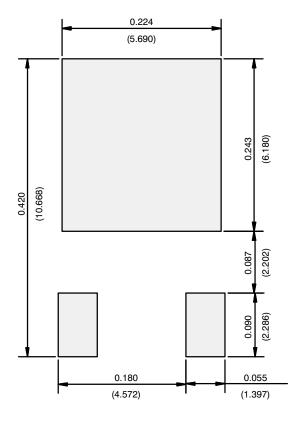
- Dimension L3 is for reference only.
- Xi'an, Mingxin, and GEM SH actual photo.



Revision: 03-Jun-13 Document Number: 71197



## **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

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Revision: 02-Oct-12 Document Number: 91000